Empa
Materials Science and Technology

ÉCOLE POLYTECHNIQUE FÉDÉRALE DE LAUSANNE

Laser Processing of Materials

Ablation Model

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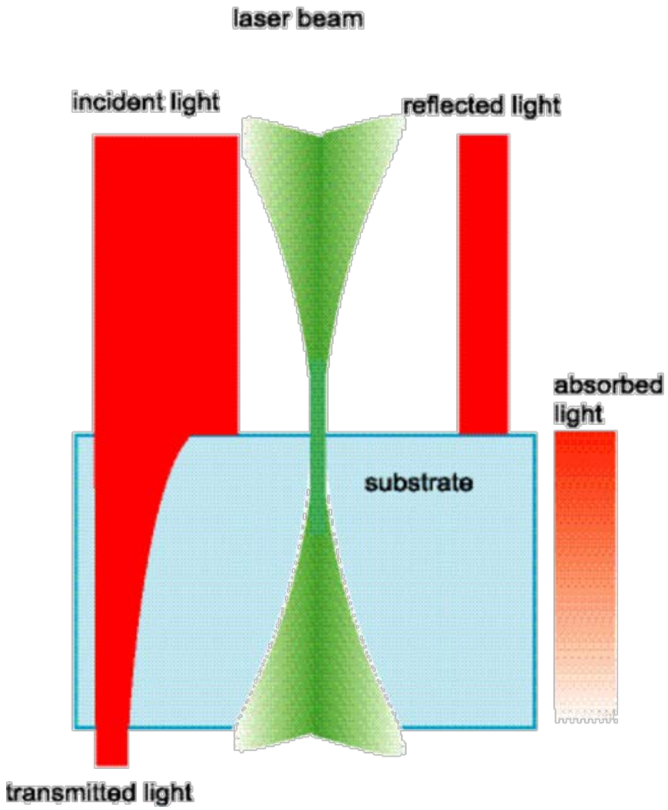
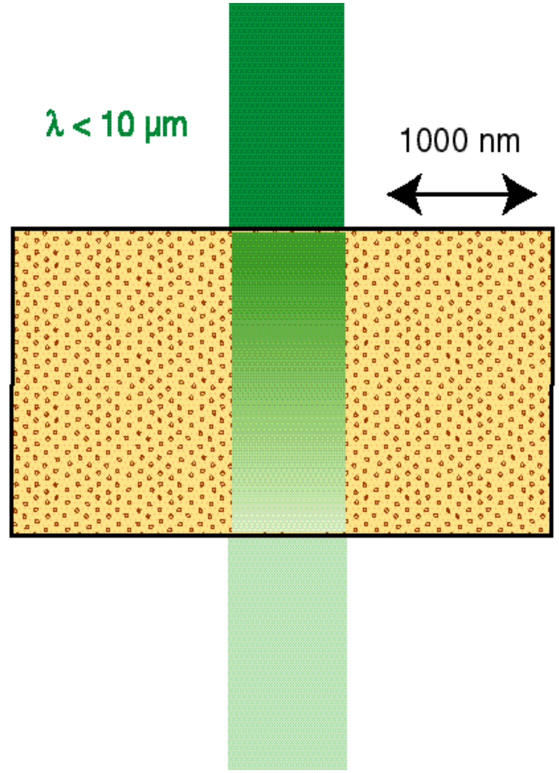
UV- Excimer Laser Ablation

- Model
- Influences
- Examples
- Applications

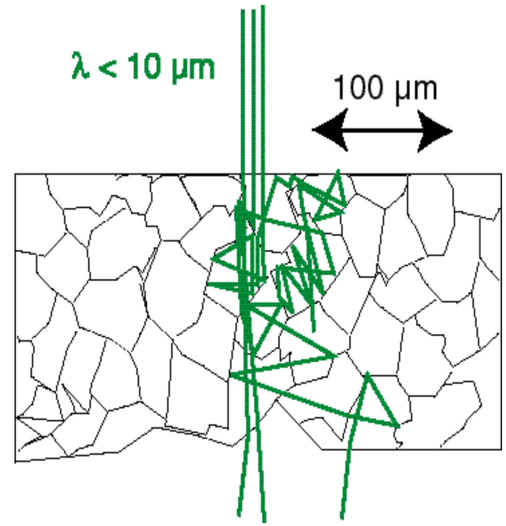
D. Bäuerle; Laser Processing and Chemistry,
3rd Edititon, Springer Berlin, 2000

Laser light material interaction





flat composit

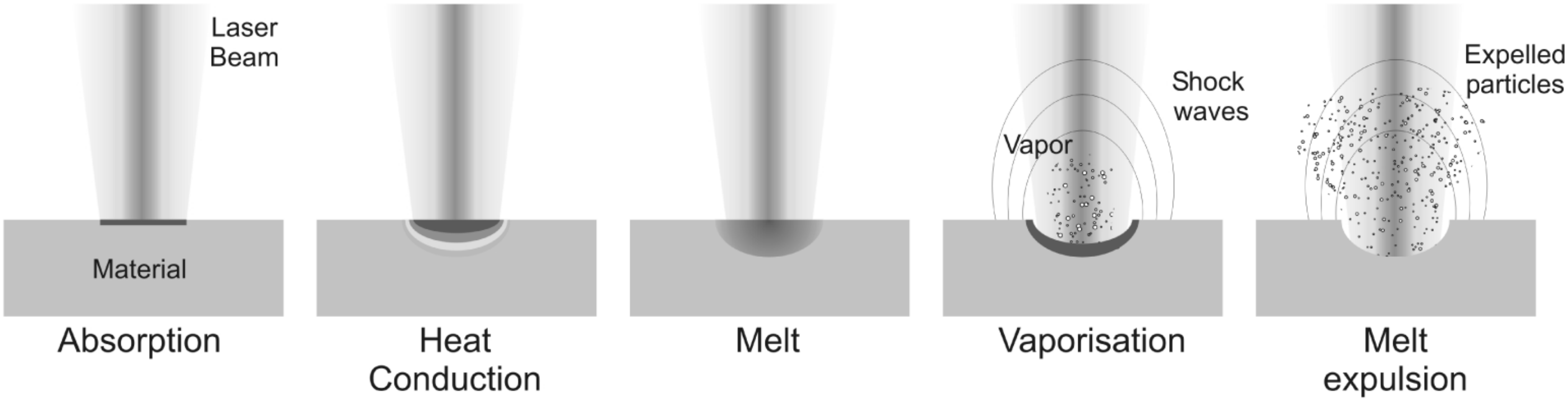


micro- macro-
structured

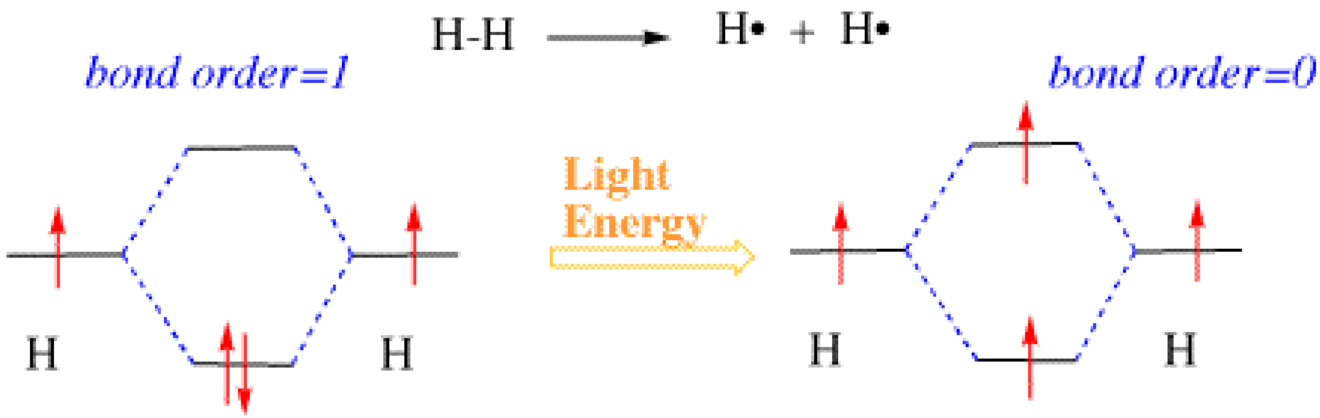
- Flat homogeneous

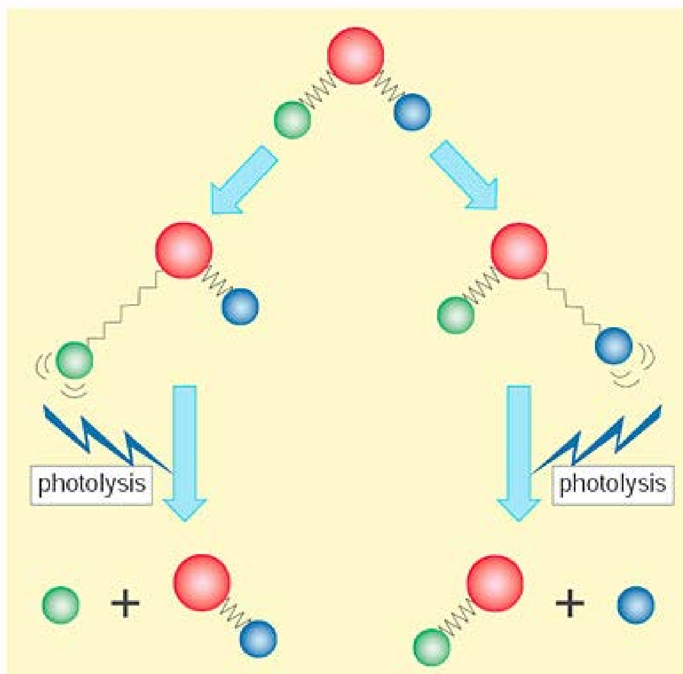
How is rough homogeneus ?

Thermal Influence

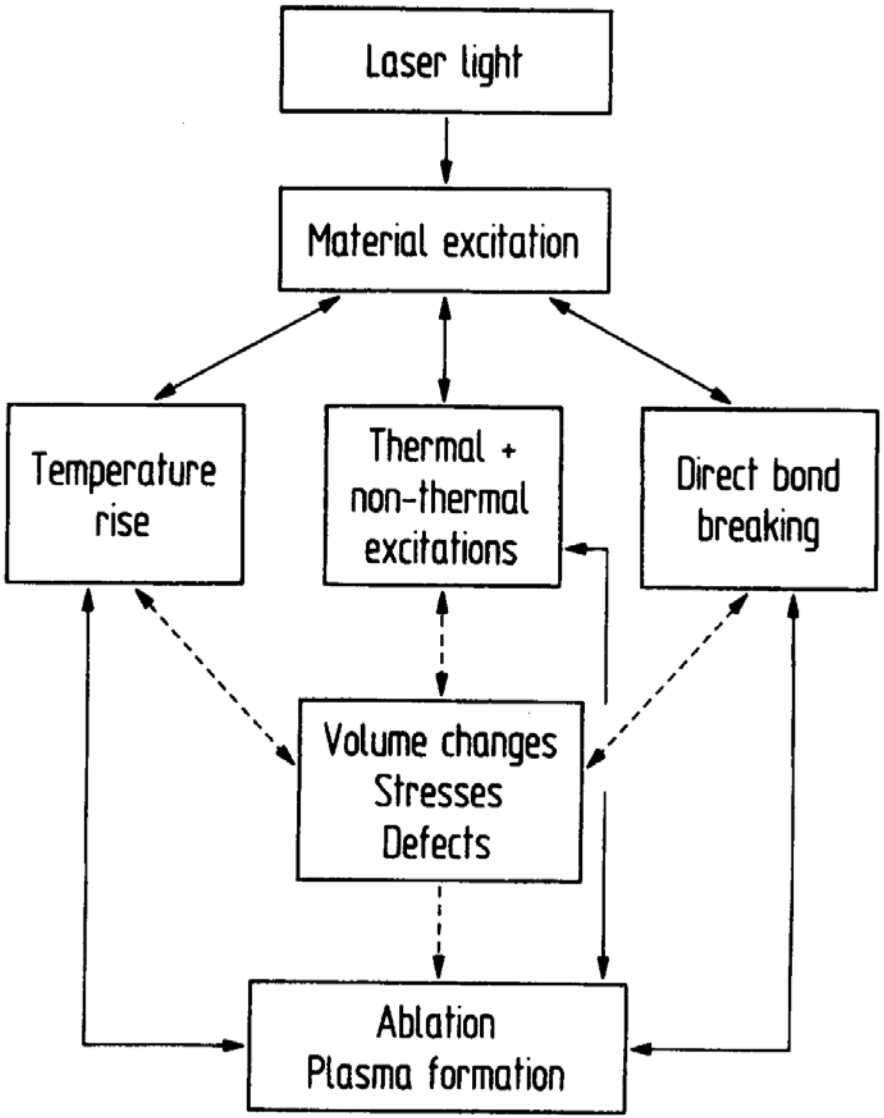


Photolysis – Direct Bond Breaking

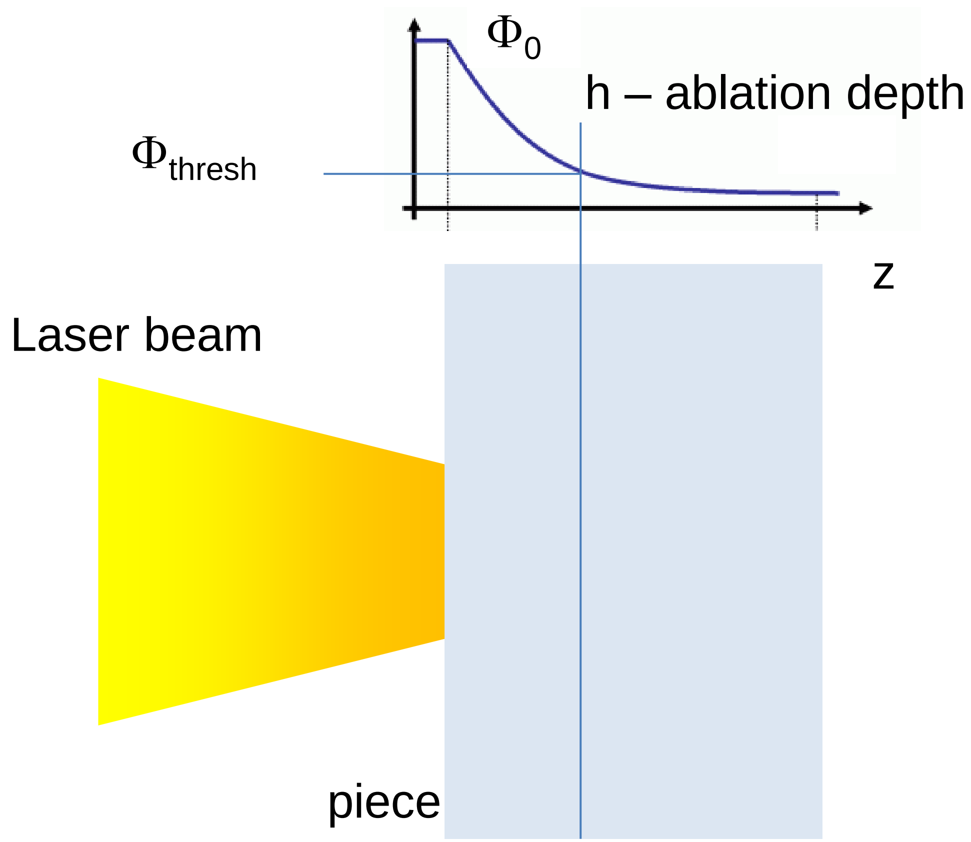




Ablation model



Ablation Depth



Physical Model

$$\Phi(d) = \Phi_{\exp}^{-\alpha_{eff} \cdot d}$$

Lambert-Beer's absorption law

$$\Phi_{\Delta h} = \Phi_{thresh} = \Phi_0^{-\alpha_{eff} \cdot \Delta h}$$

threshold fluence is still reached at Δh depth

$$\Delta h(\Phi) = l_{\alpha_{eff}} \ln \Phi - l_{\alpha_{eff}} \ln \Phi_{thresh}.$$

ablation rate vs. fluence dependance

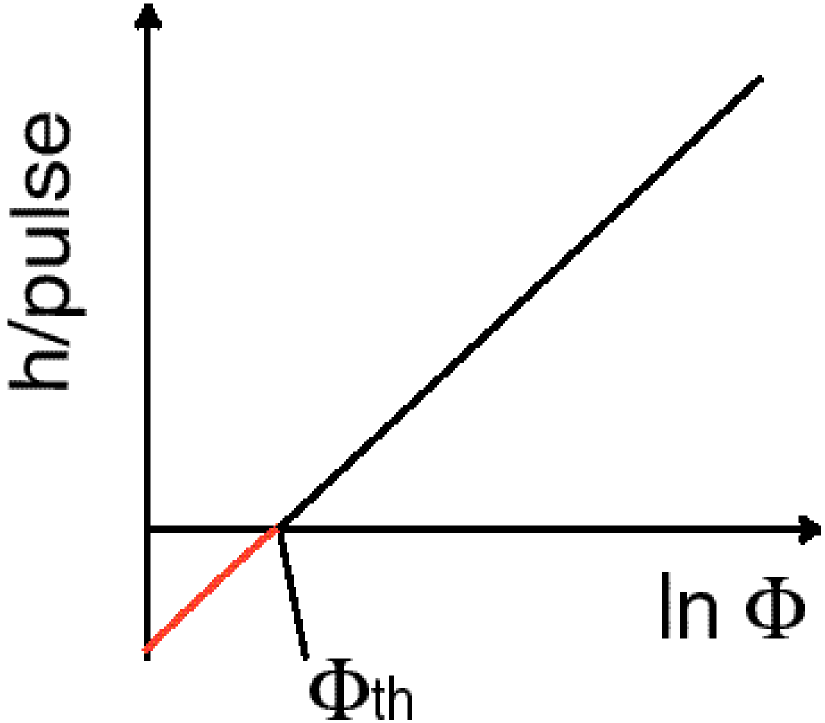
Effective Absorption Coefficient

$$\alpha_{eff} = \alpha_0 + \sigma_D N_D + \alpha_i(N) + \alpha^{NL}$$

α_0 = **linear absorption coefficient**

σ_D = **Dopant cross section**

Limits: no sense at extremely high laser powers, avalanche ionization



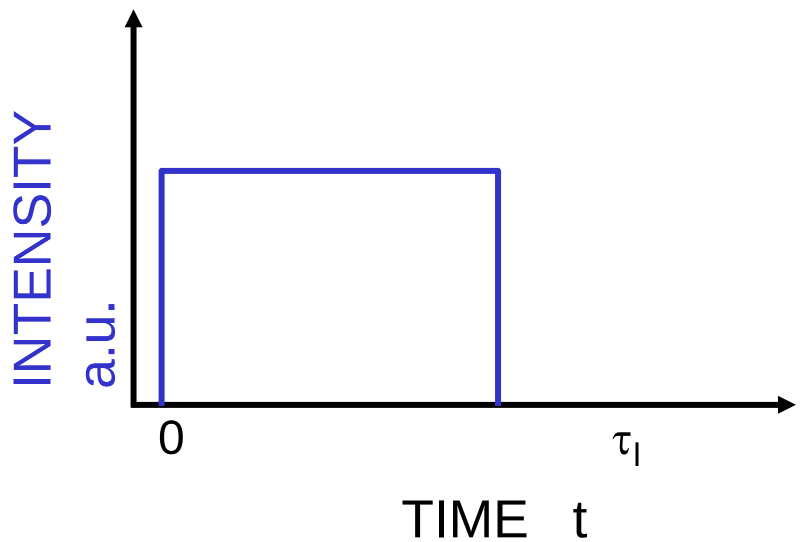
Single Pulse Ablation

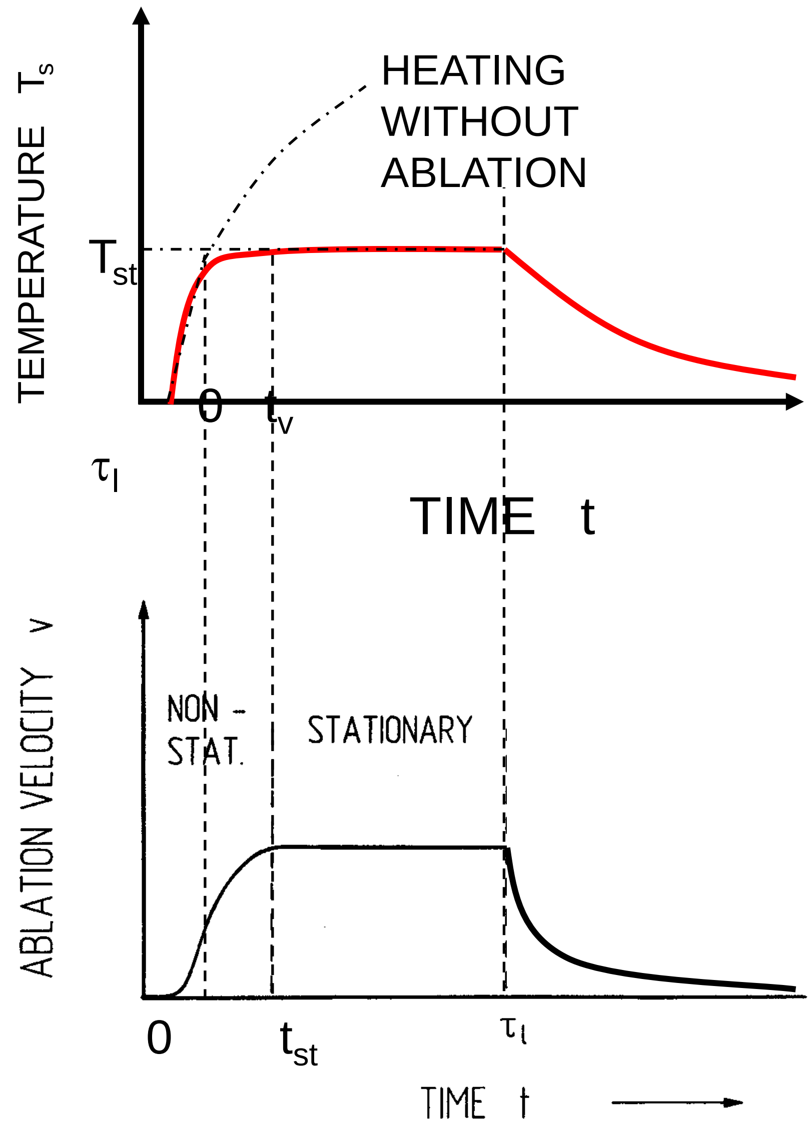
Photothermal ablation

$\tau_T \ll \tau_{des}$ **pure thermal ablation,IR, vis and many UV**

Assumptions:

- **homogeneous irradiation**
- $w \gg l_{th};\ l_\alpha$
- **no stress**
- **no T dependence**





Single pulse ablation

- Influence of pulse duration

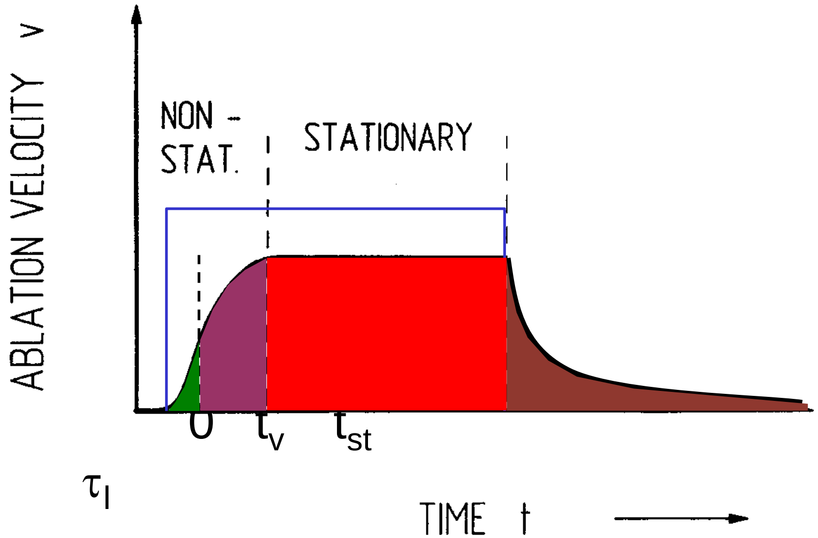
$$\Delta h = \int_0^\infty v(t)dt \approx \Delta h_1 + \Delta h_2 + \Delta h_3 + \Delta h_4$$

$$\Delta h_1 \equiv \Delta h_1(t \le t_v)$$

$$\Delta h_2 \equiv \Delta h_2(t_v \le t \le t_{st})$$

$$\Delta h_3 \equiv \Delta h_3(t_{st} \le t \le \tau_l)$$

$$\Delta h_4 \equiv \Delta h_4(t \ge \tau_l)$$



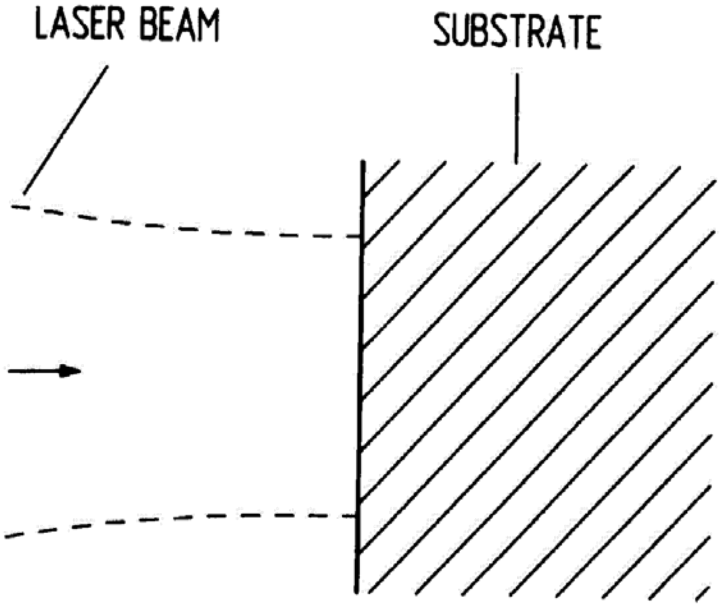
Δh_1 to be ignored in all cases

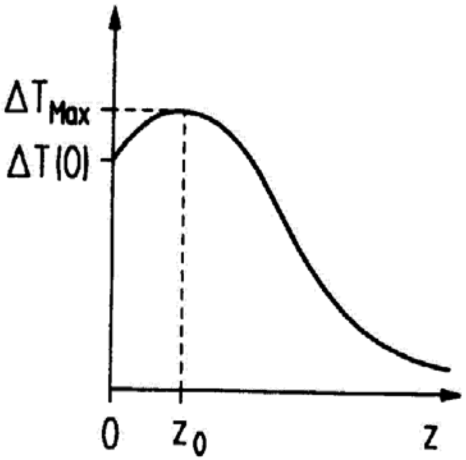
fs, ps ablation Δh_4

µs, ms ablation Δh_3

ns ablation Δh_2, Δh_3, Δh_4

Pulsed Laser Ablation





Interaction 193 nm Excimer light with materials

- Optical penetration depth:

$$l_\alpha = \frac{1}{\alpha}$$

- Thermal penetration depth:

$$l_{th} = 2\sqrt{D\tau_l}$$

	l_α	l_{th}
Al	**10 nm**	**2.80 μm**
Mo	**< 30 nm**	**2.04 μm**
SiO_2	**3.3 m**	**270 nm**
PET	**30 nm**	**90 nm**

α: optical absorption coefficient [cm^{-1}]

D: thermal diffusivity [cm^2 /s]

τ_l: pulse duration

Pulsed Laser Ablation (PLA)

- How much material is taken off per laser pulse ?

$$\Delta h \approx \max(l_{th}, l_{\alpha})$$

What are the physical steps ?

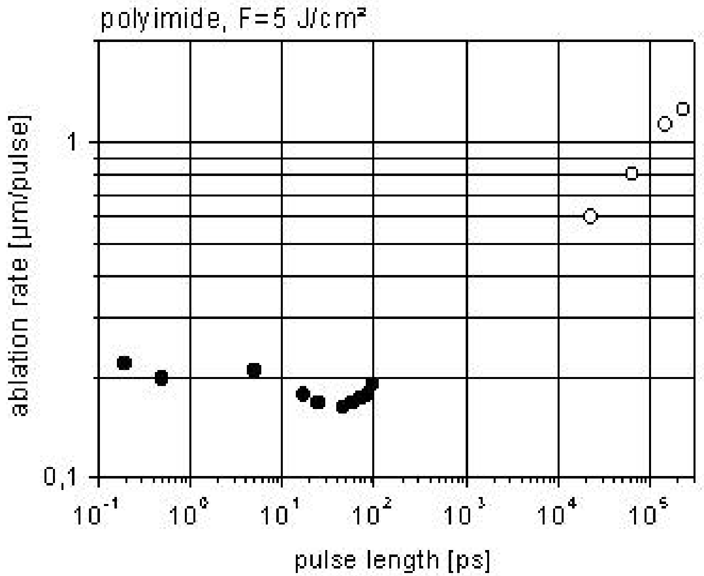
Optical absorption

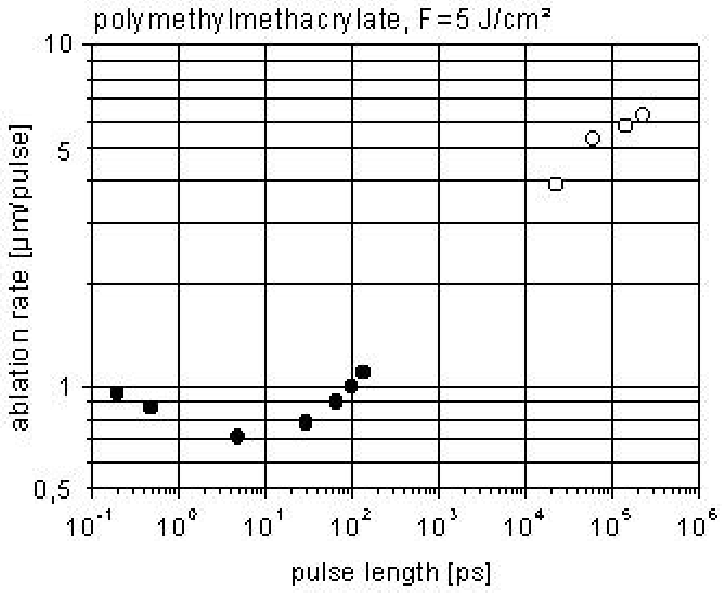
Energy dissipation

Decomposition

Material removal

Ablation rate dependance: Pulse duration





Conclusions

Ablation Process characteristics

threshold value for Laser light fluence ϕ_{th}

$$\phi_{th_{oxides}} = 0.5 - 2 \quad [J/cm^2]$$

$$\phi_{th_{polymers}} = 0.01 - 1 \quad [J/cm^2]$$

ablation depth per pulse : $\Delta h \leq max(l_T, l_\alpha)$

with

the heat penetration depth l_T :

$$l_T \approx 2\sqrt{D\tau_l}$$

including the laser pulse length τ_l

and the thermal diffusivity $D = \kappa/(\rho\, c_p)$

$$D_{metals} = 0.1 - 2 \quad [cm^2/s]$$

$$D_{oxides} = 0.01 - 1 \quad [cm^2/s]$$

$$D_{polymers} = 0.001 - 0.01 \quad [cm^2/s]$$

the light penetration depth l_α :

$$l_\alpha = \alpha^{-1}$$

Is Cold Laser Processing possible ?

High vacuum molecule photon interactions:
Excitation by absorption – thermal relaxation (10^{-14} – 10^{-6} s) useful for isotope separation, polyatomic molecules, (10^{-13} – 10^{-11} s)

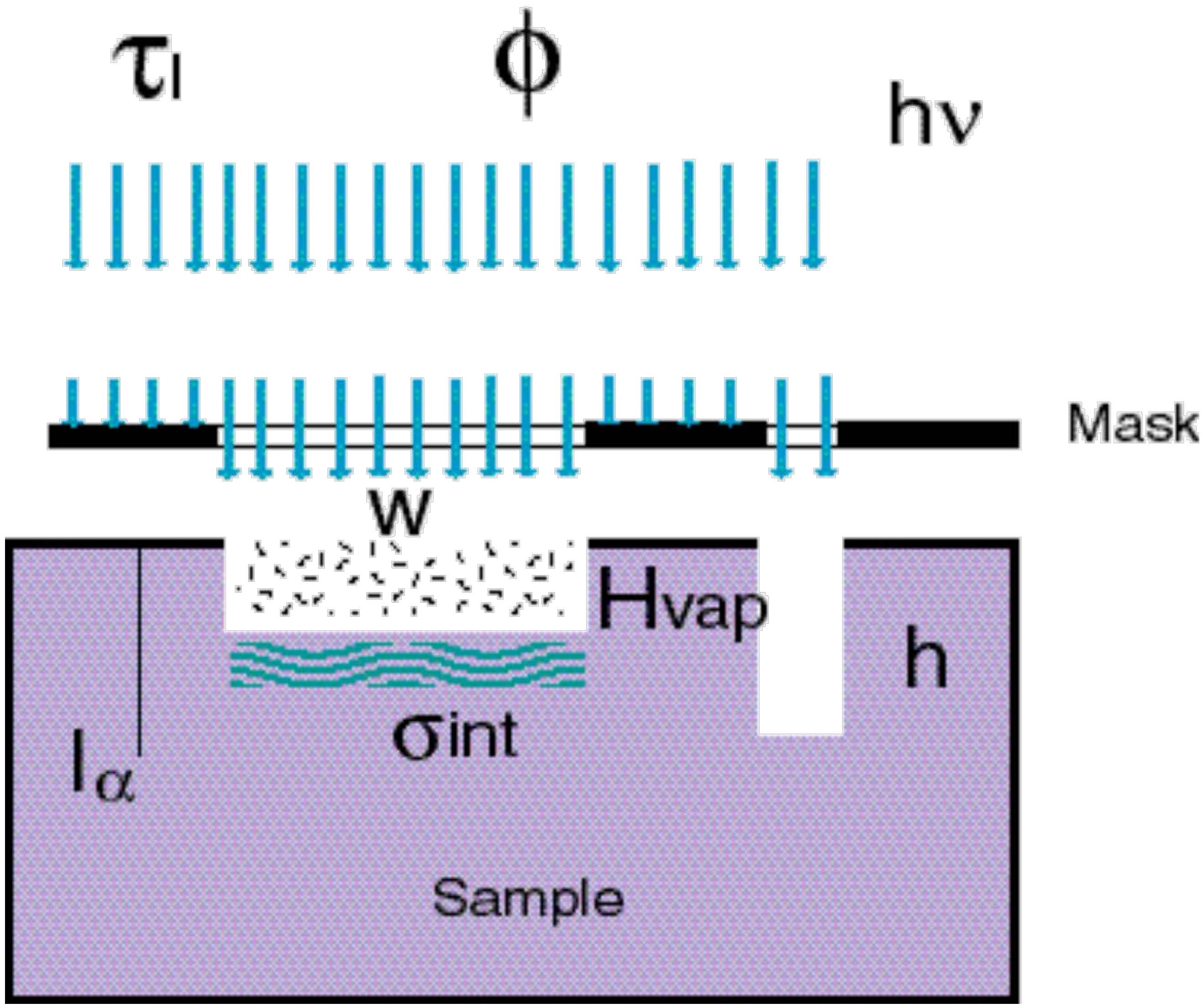
Generally in liquids and solids:

Excitation by absorption – thermal relaxation τ_T

Metals & Semicond. (el-el) 10^{-14}-10^{-13} s ; (el-phon) 10^{-12}-10^{-6} s

Check thermal effects: The heat equation

Ablation – complex phenomenon



Excimer Laser model

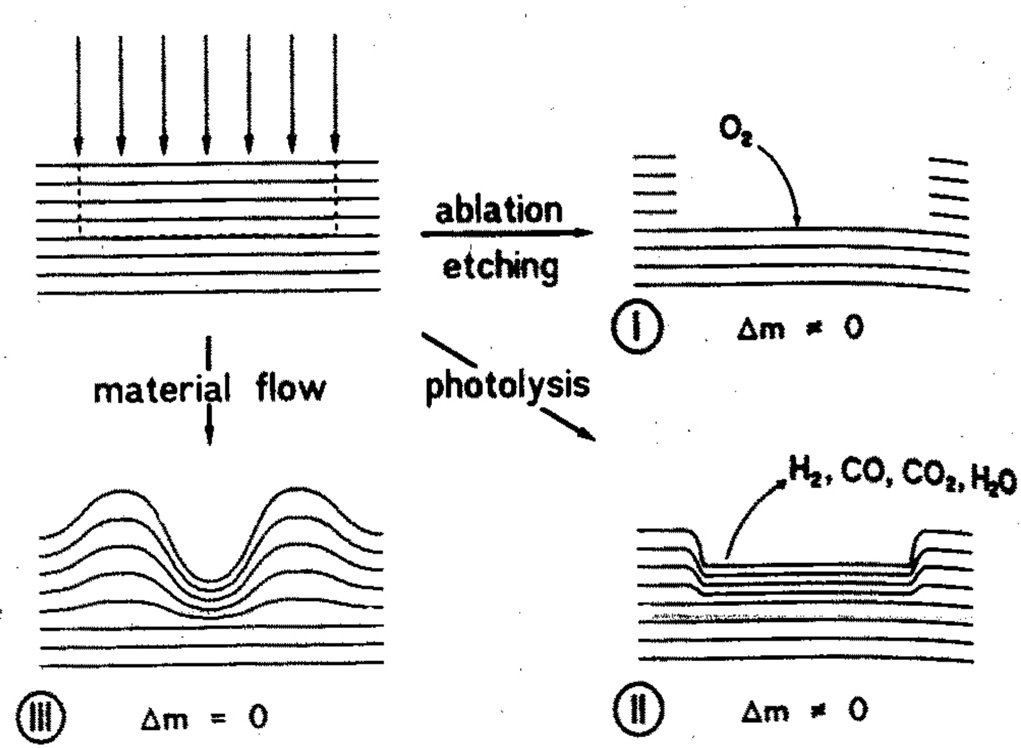
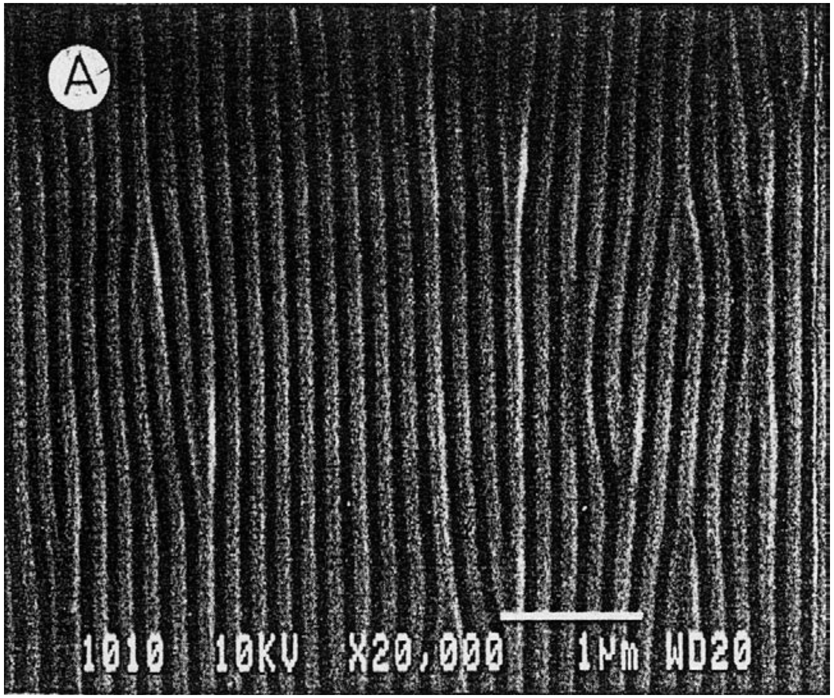


FIG. 13. Three models of photoactivated surface corrugation; (I) ablation or etching; (II) photolysis; (III) is material flow. Processes I and II are accompanied with mass decrease, even in vacuum, whereas III operates at constant mass.



Ceramics Ablation Examples

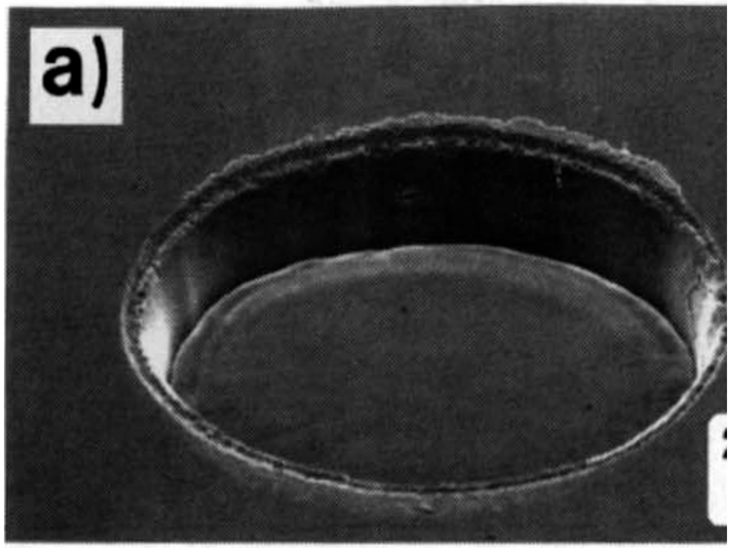
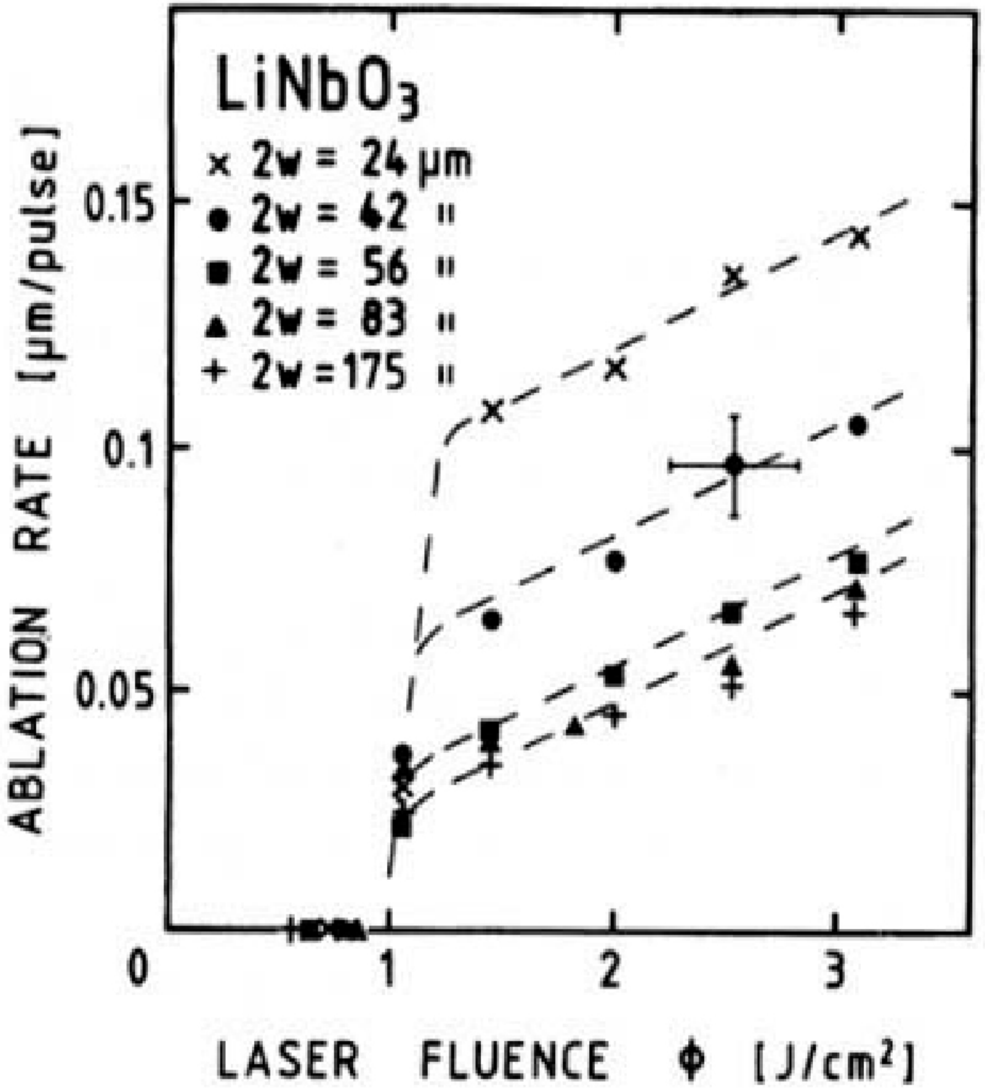
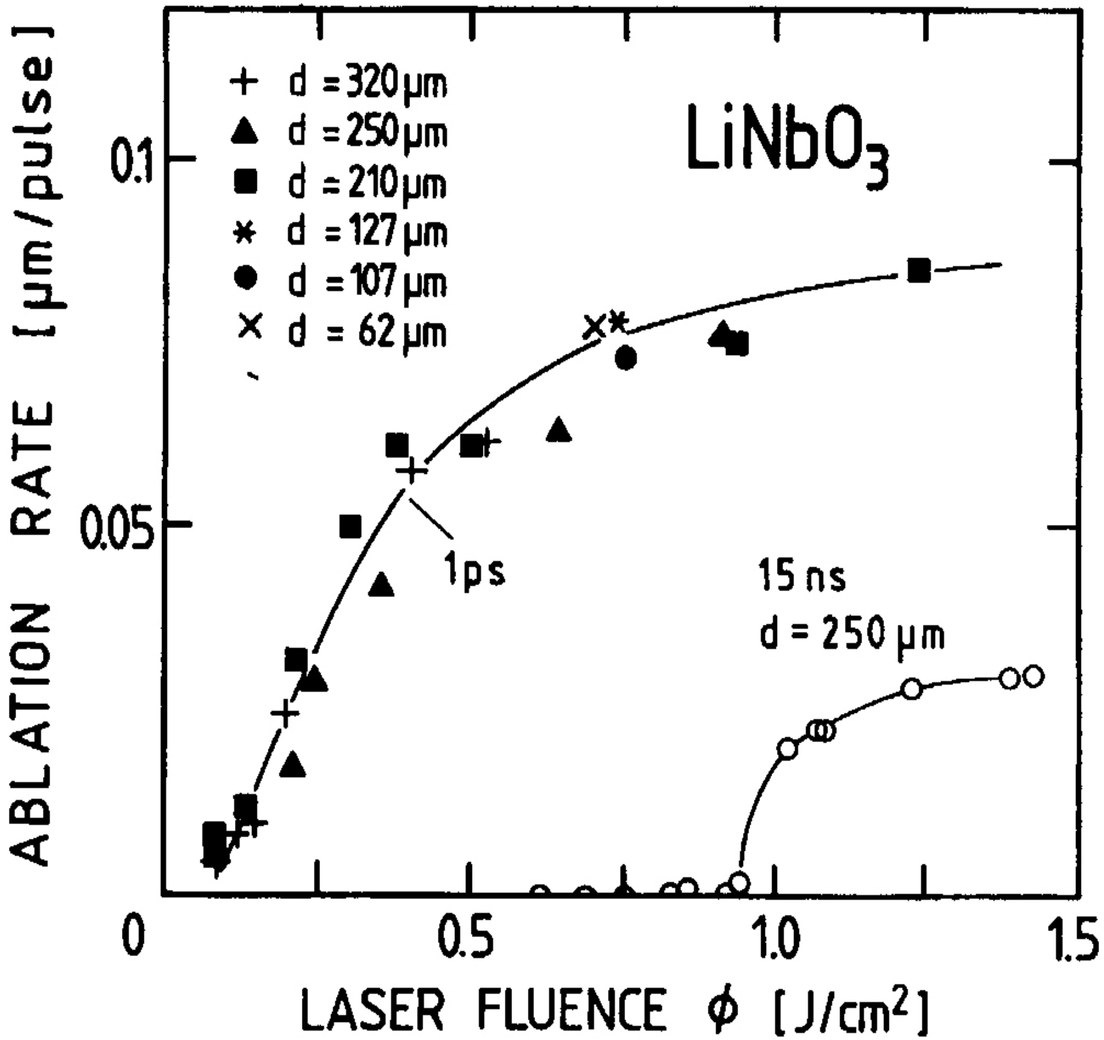
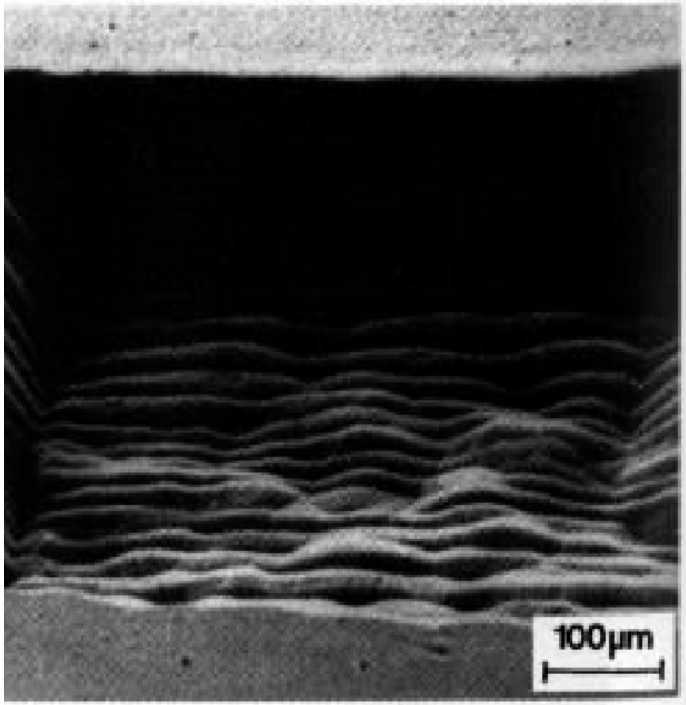


Fig. 12.1.2a,b. Projection patterning by ($\lambda = 308$ nm, $\phi = 2.7$ J/cm^2, $2w = 175$ μr $YBa_2Cu_3O_7$ film on (100) $SrTiO_3$ sub [*Heitz* et al. 1990]



Ablation Influences





48 nm KrF-laser radiation. (a) Irradi-
$= 4.2\ J/cm^2$). An undefined crater is
naterial. (b) Irradiation with fs pulses
elatively smooth and no cracks are